

Cinterion® ELS31-V/ELS51-V

Hardware Interface Overview

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1 Introduction

This document¹ describes the hardware of the Cinterion[®] ELS31-V and ELS51-V modules for Verizon Network. It helps you quickly retrieve interface specifications, electrical and mechanical details and information on the requirements to be considered for integrating further components

The ELS31-V and ELS51-V modules include a baseband, a complete dual band RF frontend, memory and required circuitry to meet 3GPP E-UTRA (Long Term Evolution - LTE, Release 10 set of specifications) and Verizon Wireless LTE UE specifications.

The module variants differentiate a follows:

- ELS31-V provides LTE connectivity with IP Services
- ELS51-V adds a Linux execution environment available for customer applications

Note: Throughout the document ELS31-V refers to ELS31-V Release 2.

1.1 Key Features at a Glance

| Feature | Implementation |
|-------------------------------------------|-----------------------------------------------------------------------------------------------|
| General | |
| Frequency bands | LTE dualband: B4, B13 |
| Output power | Class 3 (+23dBm +-2dB) for LTE AWS, LTE B4 Class 3 (+23dBm +-2dB) for LTE 700, LTE FDD B13 |
| Power supply | 3.3V to 4.5V |
| Operating temperature (board temperature) | Normal operation: -30°C to +80°C Extended operation: -40°C to +90°C |
| Physical | Dimensions: 27.6mm x 18.8mm x 2.2mm Weight: approx. 3g |
| RoHS | All hardware components fully compliant with EU RoHS Directive |
| LTE features | |
| 3GPP Release 9 | DL 10Mbps, UL 5Mbps LTE Cat. 1 data rates |
| SMS | Point-to-point MT and MO Text and PDU mode Storage in mobile equipment |
| Software | |
| AT commands | Hayes, 3GPP TS 27.007, TS 27.005, product specific |
| SIM Application Toolkit | SAT Release 99 |
| Firmware update | Generic update from host application over ASC0 or USB modem OTA over ASC0 and over USB |

^{1.} The document is effective only if listed in the appropriate Release Notes as part of the technical documentation delivered with your Gemalto M2M product.

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| Feature | Implementation |
|----------------------------|----------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------|
| Interfaces | |
| Module interface | Surface mount device with solderable connection pads (SMT application interface). Land grid array (LGA) technology ensures high solder joint reliability and allows the use of an optional module mounting socket. |
| | For more information on how to integrate SMT modules see also [4]. This application note comprises chapters on module mounting and application layout issues as well as on SMT application development equipment. |
| USB | USB 2.0 High Speed (480Mbit/s) device interface, Full Speed (12Mbit/s) compliant |
| 2 serial interfaces | ASC0: 8-wire modem interface with status and control lines, unbalanced, asynchronous Default baud rate: 115,200 baud Adjustable baud rates: 1,200 to 921,600, no autobauding support Supports RTS0/CTS0 hardware flow control. indication of incoming data/SMS on RING0 (can be used to wake up host from power down modes) |
| | ELS51-V only: ASC1 (shared with GPIO lines): 4-wire, unbalanced asynchronous interface Default baud rate: 115,200 baud Adjustable baud rates: 1,200bps to 921,600bps Supports RTS1/CTS1 hardware flow control |
| UICC interface | Supported SIM/USIM cards: 3V, 1.8V |
| Embedded UICC | Module is prepared for an embedded UICC |
| GPIO interface | 20 pads of the application interface programmable as GPIO pads (17) or GPO pads (3): GP(I)Os can be configured as COUNTER, FST_SHDN, ASC0, ASC1, and SPI signal lines Programming is done via AT commands |
| I ² C interface | Supports I ² C serial interface |
| SPI interface | Supports SPI interface |
| SDIO | ELS51-V only: 4 wire interface. |
| HSIC | ELS51-V only: High Speed Interchip Communication interface. |
| ADC | Analog-to-Digital Converter with one unbalanced analog input. |
| Digitial audio interface | Hardware prepared for future use. |
| Antenna interface pads | 50Ω LTE main antenna, 50Ω LTE diversity antenna |

1.1 Key Features at a Glance

| Feature | Implementation | |
|---------------------|------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------|--|
| Power on/off, Reset | | |
| Power on/off | Switch-on by hardware signal ON Switch-off by AT command Switch off by hardware signal GPIO4/FST_SHDN instead of AT command Automatic switch-off in case of critical temperature and voltage conditions | |
| Reset | Orderly shutdown and reset by AT command Emergency reset by hardware signal EMERG_RST | |
| Evaluation kit | | |
| Evaluation module | ELS31-V / ELS51-V module soldered onto a dedicated PCB that can be connected to an adapter in order to be mounted onto the DSB75. | |
| DSB75 | DSB75 Development Support Board designed to test and type approve Gemalto M2M modules and provide a sample configuration for application engineering. A special adapter is required to connect the ELS31-V / ELS51-V evaluation module to the DSB75. | |

1.2 ELS31-V / ELS51-V System Overview

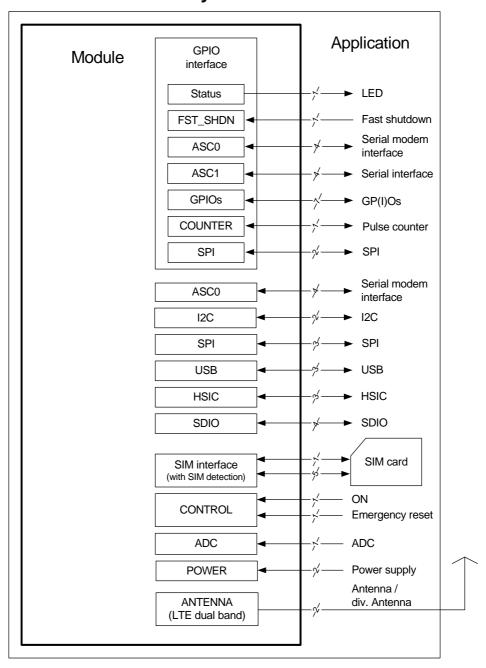


Figure 1: ELS31-V / ELS51-V system overview

2 Interface Characteristics

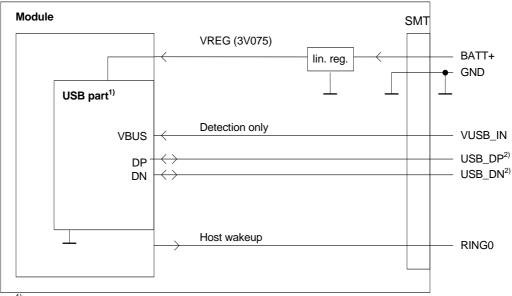
ELS31-V / ELS51-V is equipped with an SMT application interface that connects to the external application. The SMT application interface incorporates the various application interfaces as well as the RF antenna interfaces.

2.1 Application Interface

2.1.1 USB Interface

ELS31-V / ELS51-V supports a USB 2.0 High Speed (480Mbit/s) device interface that is Full Speed (12Mbit/s) compliant. The USB interface is primarily intended for use as command and data interface and for downloading firmware.

The V_{USB} line is used for cable detection only, this is to be supplied by the external device. The USB circuitry in the ELS31-V / ELS51-V is designed to meet the USB 2.0 specification for self-power.2.0".



¹⁾ It is recommended to add EMI suppression filter (see section 2.1.3.1)

Figure 2: USB circuit

To properly connect the module's USB interface to the external application, a USB 2.0 compatible connector and cable or hardware design is required. Furthermore, the USB modem driver distributed with ELS31-V / ELS51-V needs to be installed.

²⁾ If the USB interface is operated in High Speed mode (480MHz), it is recommended to take special care routing the data lines USB_DP and USB_DN. Application layout should in this case implement a differential impedance of 900hm for proper signal integrity.

^{1.} The specification is ready for download on http://www.usb.org/developers/docs/

2.1.2 Serial Interface ASC0

ELS31-V / ELS51-V offers an 8-wire unbalanced, asynchronous modem interface ASC0 conforming to ITU-T V.24 protocol DCE signalling. The electrical characteristics do not comply with ITU-T V.28. The significant levels are 0V (for low data bit or active state) and 1.8V (for high data bit or inactive state).

ELS31-V / ELS51-V is designed for use as a DCE. Based on the conventions for DCE-DTE connections it communicates with the customer application (DTE) using the following signals:

- Port TXD @ application sends data to the module's TXD0 signal line
- Port RXD @ application receives data from the module's RXD0 signal line

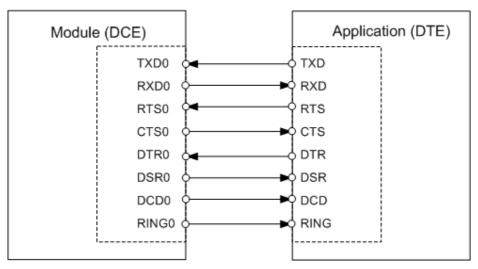


Figure 3: Serial interface ASC0

Features:

- Includes the data lines TXD0 and RXD0, the status lines RTS0 and CTS0 and, in addition, the modem control lines DTR0, DSR0, DCD0 and RING0.
- Configured for 8 data bits, no parity and 1 stop bit.
- ASC0 can be operated at fixed bit rates from 1200bps up to 921600bps.
- Supports RTS0/CTS0 hardware flow control. Communication is possible by using only RXD and TXD lines, if RTS0 is pulled low.
- Wake up from SLEEP mode by RTS0 activation (high to low transition).

2.1.3 Serial Interface ASC1 (ELS51-V Only)

ELS51-V provides a 4-wire unbalanced, asynchronous modem interface ASC1 conforming to ITU-T V.24 protocol DCE signalling. The electrical characteristics do not comply with ITU-T V.28. The significant levels are 0V (for low data bit or active state) and 1.8V (for high data bit or inactive state). With ELS31-V, ASC1 can only be used as data interface.

ELS51-V is designed for use as a DCE. Based on the conventions for DCE-DTE connections it communicates with the customer application (DTE) using the following signals:

- Port TXD @ application sends data to module's TXD1 signal line
- · Port RXD @ application receives data from the module's RXD1 signal line

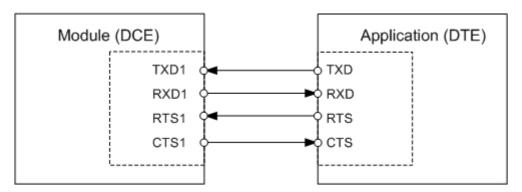


Figure 4: Serial interface ASC1

Features

- Includes only the data lines TXD1 and RXD1 plus RTS1 and CTS1 for hardware handshake.
- On ASC1 no RING line is available.
- Configured for 8 data bits, no parity and 1 or 2 stop bits.
- ASC1 can be operated at fixed bit rates from 1,200 bps to 921600 bps.
- Supports RTS1/CTS1 hardware flow control. Communication is possible by using only RXD and TXD lines, if RTS1 is pulled low.
- Wake up from SLEEP mode by RTS0 activation (high to low transition).

2.1.4 UICC/SIM/USIM Interface

ELS31-V / ELS51-V has an integrated UICC/SIM/USIM interface compatible with the 3GPP 31.102 and ETSI 102 221. This is wired to the host interface in order to be connected to an external SIM card holder. Five pads on the SMT application interface are reserved for the SIM interface.

The UICC/SIM/USIM interface supports 3V and 1.8V SIM cards.

The CCIN signal serves to detect whether a tray (with SIM card) is present in the card holder. Using the CCIN signal is mandatory for compliance with the GSM 11.11 recommendation if the mechanical design of the host application allows the user to remove the SIM card during operation. To take advantage of this feature, an appropriate SIM card detect switch is required on the card holder. For example, this is true for the model supplied by Molex, which has been tested to operate with ELS31-V / ELS51-V and is part of the Gemalto M2M reference equipment submitted for type approval. See Section 7.1 for Molex ordering numbers.

Table 1: Signals of the SIM interface (SMT application interface)

| Signal | Description |
|--------|------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------|
| GND | Separate ground connection for SIM card to improve EMC. |
| CCCLK | Chipcard clock |
| CCVCC | SIM supply voltage. |
| CCIO | Serial data line, input and output. |
| CCRST | Chipcard reset |
| CCIN | Input on the baseband processor for detecting a SIM card tray in the holder. If the SIM is removed during operation the SIM interface is shut down immediately to prevent destruction of the SIM. The CCIN signal is by default low and will change to high level if a SIM card is inserted. The CCIN signal is mandatory for applications that allow the user to remove the SIM card during operation. The CCIN signal is solely intended for use with a SIM card. It must not be used for any other purposes. Failure to comply with this requirement may invalidate the type approval of ELS31-V / ELS51-V. |

Note: No guarantee can be given, nor any liability accepted, if loss of data is encountered after removing the SIM card during operation. Also, no guarantee can be given for properly initializing any SIM card that the user inserts after having removed the SIM card during operation. In this case, the application must restart ELS31-V / ELS51-V.

The figure below shows a circuit to connect an external SIM card holder.

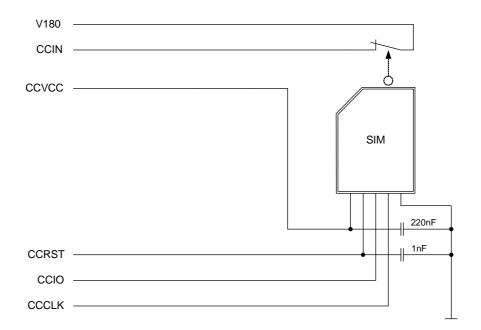


Figure 5: External UICC/SIM/USIM card holder circuit

The total cable length between the SMT application interface pads on ELS31-V / ELS51-V and the pads of the external SIM card holder must not exceed 100mm in order to meet the specifications of 3GPP TS 51.010-1 and to satisfy the requirements of EMC compliance.

To avoid possible cross-talk from the CCCLK signal to the CCIO signal be careful that both lines are not placed closely next to each other. A useful approach is using a GND line to shield the CCIO line from the CCCLK line.

2.1.5 GPIO Interface

ELS31-V / ELS51-V offers a GPIO interface with 17 GPIO and 3 GPO lines. The lines are shared with other interfaces or functions: Fast shutdown (see Section 2.1.11.2), status LED (see Section 2.1.11.1), a pulse counter (see Section 2.1.8), ASC0 (see Section 2.1.2), ASC1 (see Section 2.1.3), SPI (see Section 2.1.7), and HSIC (see Section 2.1.9).

The following table shows the configuration variants for the GPIO pads. All variants are mutually exclusive, i.e. a pad configured for instance as Status LED is locked for alternative usage.

Table 2: GPIO lines and possible alternative assignment

| GPIO | Fast Shutdown | Status LED | Pulse Counter | ASC0 | ASC1 | SPI | HSIC |
|--------|------------------|---------------|------------------|-------|------|---------|-------------|
| GPIO1 | | | | DTR0 | | | |
| GPIO2 | | | | DCD0 | | | |
| GPIO3 | | | | DSR0 | | | |
| GPIO4 | FST_SHDN | | | | | | |
| GPO5 | | LED | | | | | |
| GPIO6 | | | | | | | |
| GPIO7 | | | | | | | |
| GPIO8 | | | COUNTER | | | | |
| GPIO16 | | | | | RXD1 | | AP_WAKEUP |
| GPIO17 | | | | | TXD1 | | HOST_ACTIVE |
| GPIO18 | | | | | RTS1 | | CP_WAKEUP |
| GPIO19 | | | | | CTS1 | | SUSPEND |
| GPIO20 | | | | | | | |
| GPIO21 | | | | | | | |
| GPIO22 | | | | | | | |
| GPO23 | | | | | | | |
| GPIO24 | | | | RING0 | | | |
| GPIO25 | | | | | | | |
| GPO26 | | | | | | SPI_CS1 | |
| GPIO27 | | | | | | SPI_CS2 | |

After startup, the above mentioned alternative GPIO line assignments can be configured using AT commands (see [1]). The configuration is non-volatile and available after module restart.

Notes:

gemalto^x

GPO5, GPO23 and GPO26 are GPOs only.

2.1.6 I²C Interface

I²C is a serial, 8-bit oriented data transfer bus for bit rates up to 400kbps in Fast mode. It consists of two lines, the serial data line I2CDAT and the serial clock line I2CCLK. The module acts as a single master device, e.g. the clock I2CCLK is driven by the module. I2CDAT is a bi-directional line. Each device connected to the bus is software addressable by a unique 7-bit address, and simple master/slave relationships exist at all times. The module operates as master-transmitter or as master-receiver. The customer application transmits or receives data only on request of the module.

The I²C interface can be powered via the V180 line of ELS31-V / ELS51-V. If connected to the V180 line, the I²C interface will properly shut down when the module enters the Power Down mode.

Note: Good care should be taken when creating the PCB layout of the host application: The traces of I2CCLK and I2CDAT should be equal in length and as short as possible.

2.1.7 SPI Interface

Four ELS31-V / ELS51-V GPIO interface lines can be configured as Serial Peripheral Interface (SPI). The SPI is a synchronous serial interface for control and data transfer between ELS31-V / ELS51-V and the external application. Only one application can be connected to the SPI and the interface supports only master mode. The transmission rates are up to 6.5Mbit/s. The SPI interface comprises the two data lines MOSI and MISO, the clock line SPI_CLK a well as the chip select lines SPI_CS1 and SPI_CS2.

2.1.8 Pulse Counter

The GPIO8 line can be configured as pulse counter line COUNTER. The pulse counter interface can be used, for example, as a clock (for GPIOs see Section 2.1.5).

2.1.9 HSIC Interface (ELS51-V Only)

TBD

2.1.10 SDIO Interface (ELS51-V Only)

TBD

2.1.11 Control Signals

2.1.11.1 Status LED

The GPO5 interface line can be configured to drive a status LED that indicates different operating modes of the module (for GPIOs see Section 2.1.5). GPO and LED functionality are mutually exclusive.

2.1.11.2 Fast Shutdown

The GPIO4 interface line can be configured as fast shutdown signal line FST_SHDN. The configured FST_SHDN line is an active low control signal.

2.2 RF Antenna Interface

The RF interface has an impedance of 50Ω . ELS31-V /ELS51-V is capable of sustaining a total mismatch at the antenna line without any damage, even when transmitting at maximum RF power.

The external antenna must be matched properly to achieve best performance regarding radiated power, modulation accuracy and harmonic suppression. Antenna matching networks are not included on the ELS31-V / ELS51-V module and should be placed in the host application if the antenna does not have an impedance of 50Ω .

Regarding the return loss ELS31-V / ELS51-V provides the following values in the active band:

Table 3: Return loss in the active band

| State of module | Return loss of module | Recommended return loss of application |
|-----------------|-----------------------|----------------------------------------|
| Receive | ≥ 8dB | ≥ 12dB |
| Transmit | not applicable | ≥ 12dB |

2.2.1 Antenna Installation

The antenna is connected by soldering the antenna pads (RF_OUT, pad #59 and DIV_ANT, pad 56) its neighboring ground pads (GND, i.e., pads #55, #57, #58 and #60) directly to the application's PCB. The antenna pad is the antenna reference point (ARP) for ELS31-V / ELS51-V. All RF data specified throughout this document is related to the ARP.

The distance between the antenna RF pads and its neighboring GND pads has been optimized for best possible impedance. On the application PCB, special attention should be paid to these 3 pads, in order to prevent mismatch.

The wiring of the antenna connection line, starting from the antenna pad to the application antenna should result in a 50Ω line impedance. Line width and distance to the GND plane needs to be optimized with regard to the PCB's layer stack.

To prevent receiver desensitization due to interferences generated by fast transients like high speed clocks on the application PCB, it is recommended to realize the antenna connection line using embedded Stripline rather than Micro-Stripline technology.

For type approval purposes, the use of a 50Ω coaxial antenna connector (U.FL-R-SMT) might be necessary. In this case the U.FL-R-SMT connector should be placed as close as possible to ELS31-V / ELS51-V's antenna pad.

2.3 Sample Application

Figure 6 shows a typical example of how to integrate a ELS31-V / ELS51-V module with an application. Usage of the various host interfaces depends on the desired features of the application.

Because of the high RF field density inside the module, it cannot be guaranteed that no self interference might occur, depending on frequency and the applications grounding concept. The potential interferers may be minimized by placing small capacitors (47pF) at suspected lines (e.g. RXD0, VDDLP, and ON).

While developing SMT applications it is strongly recommended to provide test points for certain signals, i.e., lines to and from the module - for debug and/or test purposes. The SMT application should allow for an easy access to these signals. For details on how to implement test points see [4].

The EMC measures are best practice recommendations. In fact, an adequate EMC strategy for an individual application is very much determined by the overall layout and, especially, the position of components. For example, mounting the internal acoustic transducers directly on the PCB eliminates the need to use the ferrite beads shown in the sample schematic.

Note: ELS31-V / ELS51-V is not intended for use with cables longer than 3m.

Disclaimer

No warranty, either stated or implied, is provided on the sample schematic diagram shown in Figure 6 and the information detailed in this section. As functionality and compliance with national regulations depend to a great amount on the used electronic components and the individual application layout manufacturers are required to ensure adequate design and operating safeguards for their products using ELS31-V / ELS51-V modules.

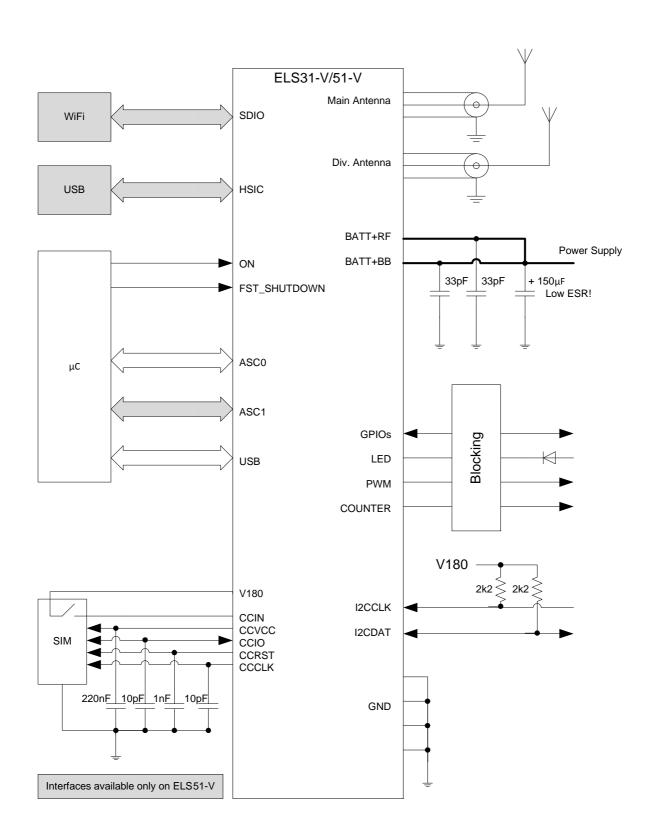


Figure 6: Schematic diagram of ELS31-V / ELS51-V sample application

3 Operating Characteristics

3.1 Operating Modes

The table below briefly summarizes the various operating modes referred to throughout the document.

Table 4: Overview of operating modes

| Mode | Function | | |
|------------------|---------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------|---------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------|--|
| Normal operation | LTE IDLE | No data transfer is in progress and the USB connection is suspended by host (or is not present) and no active communication via ASC0/ ASC1. In IDLE mode, the software can be active or in SLEEP state. | |
| | LTE DATA | LTE data transfer in progress. Power consumption depends on network settings and data transfer rate. | |
| Power Down | Normal shutdown after sending the power down command. Software is not active. Interfaces are not accessible. Operating voltage remains applied. | | |
| Airplane mode | Airplane mode shuts down the radio part of the module, causes the module to log off from the LTE network and disables all AT commands whose execution requires a radio connection. Airplane mode can be controlled by AT command (see [1]). In Airplane mode, the software can be active or in SLEEP state. | | |

3.2 Power Supply

ELS31-V/ ELS51-V needs to be connected to a power supply at the SMT application interface - 2 BATT lines and GND. There are two separate voltage domains for BATT:

- BATT_BB with a line mainly for the baseband power supply.
- BATT_RF with a line for the RF power amplifier supply.

Please note that throughout the document BATT refers to both voltage domains and power supply lines - BATT_BB and BATT_RF.

The power supply of ELS31-V / ELS51-V has to be a single voltage source at BATT_BB and BATT_RF. It must be able to provide the current for all operation modes of the module.

All the key functions for supplying power to the device are handled by the power management section of the analog controller. This IC provides the following features:

- Stabilizes the supply voltages for the baseband using low drop linear voltage regulators and a DC-DC step down switching regulator.
- Switches the module's power voltages for the power-up and -down procedures.
- SIM switch to provide SIM power supply.

4 Mechanical Dimensions, Mounting and Packaging

4.1 Mechanical Dimensions of ELS31-V / ELS51-V

Figure 7 shows the top and bottom view of ELS31-V / ELS51-V and provides an overview of the board's mechanical dimensions. For further details see Figure 8.

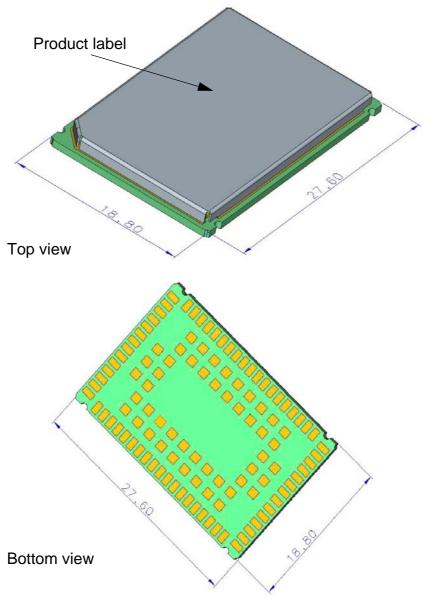


Figure 7: ELS31-V- top and bottom view

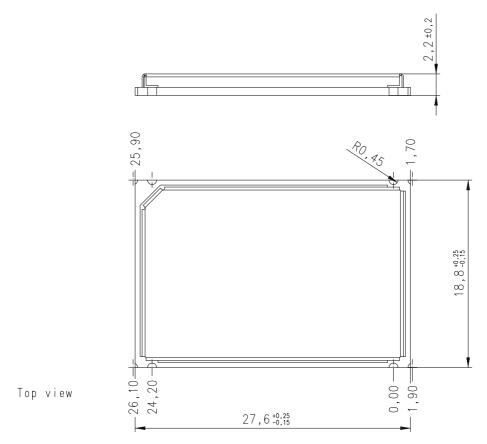


Figure 8: Dimensions of ELS31-V / ELS51-V (all dimensions in mm)

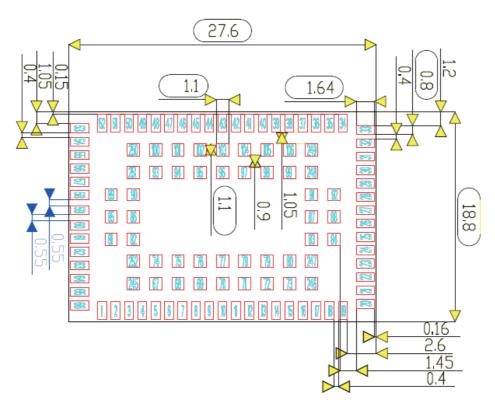


Figure 9: Dimensions of ELS31-V / ELS51-V (all dimensions in mm) - bottom view

5 Regulatory and Type Approval Information

5.1 Directives and Standards

ELS31-V / ELS51-V is designed to comply with the directives and standards listed below.

It is the responsibility of the application manufacturer to ensure compliance of the final product with all provisions of the applicable directives and standards as well as with the technical specifications provided in the "ELS31-V / ELS51-V Hardware Interface Description".

Table 5: Directives

| 2002/95/EC (RoHS 1) 2011/65/EC (RoHS 2) | Directive of the European Parliament and of the Council of 27 January 2003 (and revised on 8 June 2011) on the restriction of the use of certain hazardous substances in electrical and electronic equipment (RoHS) | RoH5 compliant |
|--------------------------------------------|---------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------|-------------------|
|--------------------------------------------|---------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------|-------------------|

Table 6: Standards of North American type approval

| CFR Title 47 | Code of Federal Regulations, Part 22 and Part 24 (Telecommunications, PCS); US Equipment Authorization FCC |
|------------------------------------|------------------------------------------------------------------------------------------------------------|
| OET Bulletin 65 (Edition 97-01) | Evaluating Compliance with FCC Guidelines for Human Exposure to Radiofrequency Electromagnetic Fields |
| UL 60 950-1 | Product Safety Certification (Safety requirements) |
| California Leadfree Mandate | Covered by European RoHS requirements |
| RSS132 (Issue2) RSS133 (Issue5) | Canadian Standard |

 Table 7: Standards of Verizon type approval

| Verizon Wireless Unified Module Process for Compliance Testing and Approval, October 2014 | | | |
|-------------------------------------------------------------------------------------------|--|--|--|
| Verizon Wireless Device Requirements LTE 3GPP Band 13 Network Access, October 2014 | | | |
| Verizon Wireless Device Requirements LTE 3GPP Band 4 Network Access, October 2014 | | | |
| 3GPP2 C.S0015-A v1.0 Short Message Service for spread spectrum systems | | | |

Table 8: Standards of GCF type approval

| 3GPP TS 51.010-1 | Digital cellular telecommunications system (Release 10); Mobile Station (MS) conformance specification; | |
|------------------|---------------------------------------------------------------------------------------------------------|--|
| GCF-CC V3.58 | Global Certification Forum - Certification Criteria | |

Table 9: Requirements of quality

| IEC 60068 | Environmental testing | | |
|--------------|-----------------------|--|--|
| DIN EN 60529 | IP codes | | |

Table 10: Standards of the Ministry of Information Industry of the People's Republic of China

| SJ/T 11363-2006 | "Requirements for Concentration Limits for Certain Hazardous Substances in Electronic Information Products" (2006-06). |
|-----------------|---------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------|
| SJ/T 11364-2006 | "Marking for Control of Pollution Caused by Electronic Information Products" (2006-06). |
| | According to the "Chinese Administration on the Control of Pollution caused by Electronic Information Products" (ACPEIP) the EPUP, i.e., Environmental Protection Use Period, of this product is 20 years as per the symbol shown here, unless otherwise marked. The EPUP is valid only as long as the product is operated within the operating limits described in the Gemalto M2M Hardware Interface Description. Please see Table 11 for an overview of toxic or hazardous substances or elements that might be contained in product parts in concentrations above the limits defined by SJ/T 11363-2006. |

Table 11: Toxic or hazardous substances or elements with defined concentration limits

| 部件名称 | 有毒有害物质或元素 Hazardous substances | | | | | |
|----------------------------------------------|--------------------------------|-----------|-----------|-----------------|---------------|-----------------|
| Name of the part | 铅 (Pb) | 汞 (Hg) | 镉 (Cd) | 六价铬 (Cr(VI)) | 多溴联苯 (PBB) | 多溴二苯醚 (PBDE) |
| 金属部件 (Metal Parts) | 0 | 0 | 0 | 0 | 0 | 0 |
| 电路模块 (Circuit Modules) | х | 0 | 0 | 0 | 0 | 0 |
| 电缆及电缆组件 (Cables and Cable Assemblies) | 0 | 0 | 0 | 0 | 0 | 0 |
| 塑料和聚合物部件 (Plastic and Polymeric parts) | 0 | 0 | 0 | 0 | 0 | 0 |

0:

表示该有毒有害物质在该部件所有均质材料中的含量均在SJ/T11363-2006 标准规定的限量要求以下。 Indicates that this toxic or hazardous substance contained in all of the homogeneous materials for this part is below the limit requirement in SJ/T11363-2006.

X:

表示该有毒有害物质至少在该部件的某一均质材料中的含量超出SJ/T11363-2006标准规定的限量要求。 Indicates that this toxic or hazardous substance contained in at least one of the homogeneous materials used for this part *might exceed* the limit requirement in SJ/T11363-2006.

5.2 SAR requirements specific to portable mobiles

Mobile phones, PDAs or other portable transmitters and receivers incorporating a GSM module must be in accordance with the guidelines for human exposure to radio frequency energy. This requires the Specific Absorption Rate (SAR) of portable ELS31V / ELS51-V based applications to be evaluated and approved for compliance with national and/or international regulations.

Since the SAR value varies significantly with the individual product design manufacturers are advised to submit their product for approval if designed for portable use. For US markets the relevant directives are mentioned below. It is the responsibility of the manufacturer of the final product to verify whether or not further standards, recommendations or directives are in force outside these areas.

Products intended for sale on US markets

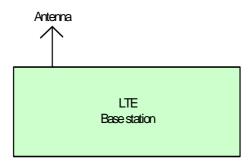
ES 59005/ANSI C95.1 Considerations for evaluation of human exposure to Electromagnetic Fields (EMFs) from Mobile Telecommunication Equipment (MTE) in the frequency range 30MHz - 6GHz

Please note that SAR requirements are specific only for portable devices and not for mobile devices as defined below:

- Portable device:
 - A portable device is defined as a transmitting device designed to be used so that the radiating structure(s) of the device is/are within 20 centimeters of the body of the user.
- Mobile device:
 - A mobile device is defined as a transmitting device designed to be used in other than fixed locations and to generally be used in such a way that a separation distance of at least 20 centimeters is normally maintained between the transmitter's radiating structure(s) and the body of the user or nearby persons. In this context, the term "fixed location" means that the device is physically secured at one location and is not able to be easily moved to another location.

5.3 Reference Equipment for Type Approval

The Gemalto M2M reference setup submitted to type approve ELS31-V / ELS51-V (including a special approval adapter for the DSB75) is shown in the following figure¹:



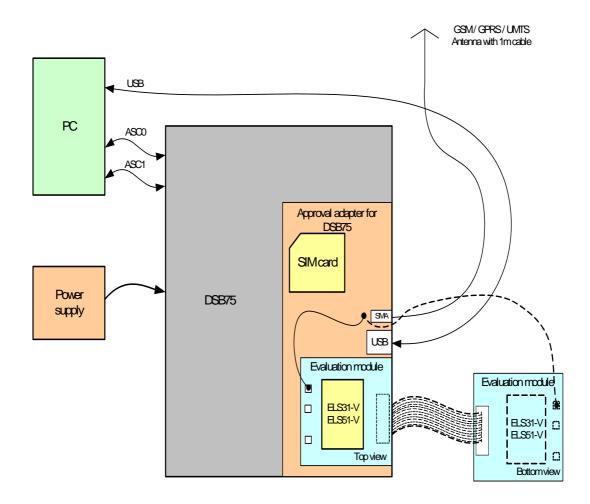


Figure 10: Reference equipment for Type Approval

For RF performance tests a mini-SMT/U.FL to SMA adapter with attached 6dB coaxial attenuator is chosen to connect the evaluation module directly to the GSM/UMTS test equipment instead of employing the SMA antenna connectors on the ELS31-V- / ELS51-V-DSB75 adapter as shown in Figure 10. The following products are recommended:

Hirose SMA-Jack/U.FL-Plug conversion adapter HRMJ-U.FLP(40)

⁽for details see see http://www.hirose-connectors.com/ or http://www.farnell.com/

Aeroflex Weinschel Fixed Coaxial Attenuator Model 3T/4T

⁽for details see http://www.aeroflex.com/ams/weinschel/pdfiles/wmod3&4T.pdf)

5.4 Compliance with FCC and IC Rules and Regulations

The Equipment Authorization Certification for the Gemalto M2M reference application described in Section 5.3 will be registered under the following identifiers:

ELS31-V:

FCC Identifier: QIPELS31-V (not yet granted)
Industry Canada Certification Number: 7830A-ELS31V (not yet granted)
Granted to Gemalto M2M GmbH

ELS51-V:

FCC Identifier: QIPELS51-V (not yet granted)
Industry Canada Certification Number: 7830A-ELS51V (not yet granted)
Granted to Gemalto M2M GmbH

Manufacturers of mobile or fixed devices incorporating ELS31-V / ELS51-V modules are authorized to use the FCC Grants and Industry Canada Certificates of the ELS31-V / ELS51-V modules for their own final products according to the conditions referenced in these documents. In this case, an FCC/ IC label of the module shall be visible from the outside, or the host device shall bear a second label stating "Contains FCC ID: QIPELS31-V" / "Contains FCC ID: QIPELS51-V", and accordingly "Contains IC: 7830A-ELS31V" / "Contains IC: 7830A-ELS51V". The integration is limited to fixed or mobile categorised host devices, where a separation distance between the antenna and any person of min. 20cm can be assured during normal operating conditions.

For mobile and fixed operation configurations the antenna gain, including cable loss, must not exceed the limits in the following Table 12 for FCC and IC.

Table 12: Antenna gain limits for FCC and IC

| Operating band | FCC limit | IC limit | Unit |
|-----------------------------------------------------------------|-----------|----------|------|
| Maximum gain in lower operating bands with f< 1GHz (LTE Bd13) | 10.4 | 7.4 | dBi |
| Maximum gain in higher operating bands with f=1700MHz (LTE Bd4) | 6.5 | 6.5 | dBi |

IMPORTANT:

Manufacturers of portable applications incorporating ELS31V / ELS51-V modules are required to have their final product certified and apply for their own FCC Grant and Industry Canada Certificate related to the specific portable mobile. This is mandatory to meet the SAR requirements for portable mobiles (see Section 5.2 for detail).

Changes or modifications not expressly approved by the party responsible for compliance could void the user's authority to operate the equipment.

Note: This equipment has been tested and found to comply with the limits for a Class B digital device, pursuant to part 15 of the FCC Rules and with Industry Canada licence-exempt RSS standard(s). These limits are designed to provide reasonable protection against harmful interference in a residential installation. This equipment generates, uses and can radiate radio frequency energy and, if not installed and used in accordance with the instructions, may cause harmful interference to radio communications. However, there is no guarantee that interference

5.4 Compliance with FCC and IC Rules and Regulations

will not occur in a particular installation. If this equipment does cause harmful interference to radio or television reception, which can be determined by turning the equipment off and on, the user is encouraged to try to correct the interference by one or more of the following measures:

- Reorient or relocate the receiving antenna.
- Increase the separation between the equipment and receiver.
- Connect the equipment into an outlet on a circuit different from that to which the receiver is connected
- Consult the dealer or an experienced radio/TV technician for help.

This Class B digital apparatus complies with Canadian ICES-003.

If Canadian approval is requested for devices incorporating ELS31V / ELS51-V modules the above note will have to be provided in the English and French language in the final user documentation. Manufacturers/OEM Integrators must ensure that the final user documentation does not contain any information on how to install or remove the module from the final product.

6 Document Information

6.1 Revision History

New document: "Cinterion® ELS31-V/ELS51-V Hardware Interface Overview" v00.502

| Chapter | What is new |
|---------|-------------------------|
| | Initial document setup. |

6.2 Related Documents

- [1] ELS31-V / ELS51-V AT Command Set
- [2] ELS31-V / ELS51-V Release Note
- [3] Application Note 40: Thermal Solutions
- [4] Application Note 48: SMT Module Integration
- [5] Universal Serial Bus Specification Revision 2.0, April 27, 2000

6.3 Terms and Abbreviations

| Abbreviation | Description |
|--------------|------------------------------------------------------------------------------------------------|
| ADC | Analog-to-digital converter |
| AGC | Automatic Gain Control |
| ANSI | American National Standards Institute |
| ARFCN | Absolute Radio Frequency Channel Number |
| ARP | Antenna Reference Point |
| ASC0/ASC1 | Asynchronous Controller. Abbreviations used for first and second serial interface of the modue |
| В | Thermistor Constant |
| BER | Bit Error Rate |
| BTS | Base Transceiver Station |
| CB or CBM | Cell Broadcast Message |
| CE | Conformité Européene (European Conformity) |
| CHAP | Challenge Handshake Authentication Protocol |
| CPU | Central Processing Unit |
| CS | Coding Scheme |
| CSD | Circuit Switched Data |
| CTS | Clear to Send |
| DAC | Digital-to-Analog Converter |

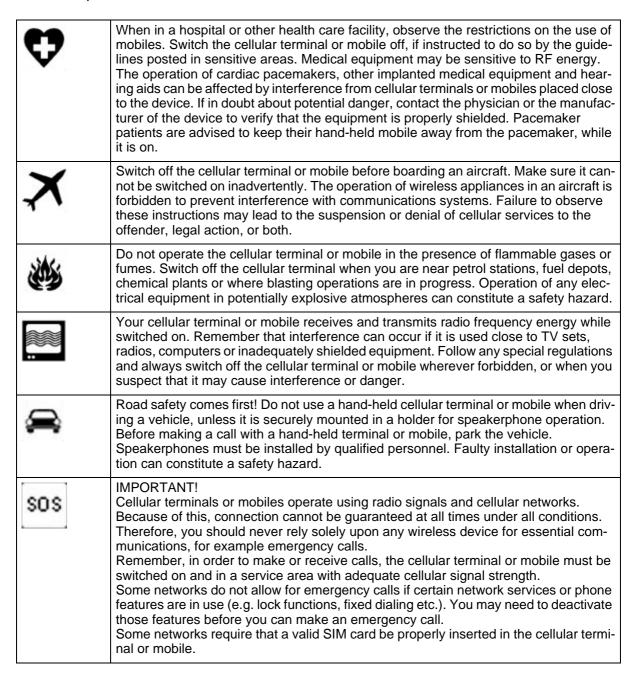
| Abbreviation | Description | | |
|--------------|--------------------------------------------------------------------------------------------------|--|--|
| DAI | Digital Audio Interface | | |
| dBm0 | Digital level, 3.14dBm0 corresponds to full scale, see ITU G.711, A-law | | |
| DCE | Data Communication Equipment (typically modems, e.g. Gemalto M2M module) | | |
| DCS 1800 | Digital Cellular System, also referred to as PCN | | |
| DRX | Discontinuous Reception | | |
| DSB | Development Support Box | | |
| DSP | Digital Signal Processor | | |
| DSR | Data Set Ready | | |
| DTE | Data Terminal Equipment (typically computer, terminal, printer or, for example, GSM application) | | |
| DTR | Data Terminal Ready | | |
| DTX | Discontinuous Transmission | | |
| EFR | Enhanced Full Rate | | |
| EGSM | Enhanced GSM | | |
| EIRP | Equivalent Isotropic Radiated Power | | |
| EMC | Electromagnetic Compatibility | | |
| ERP | Effective Radiated Power | | |
| ESD | Electrostatic Discharge | | |
| ETS | European Telecommunication Standard | | |
| FCC | Federal Communications Commission (U.S.) | | |
| FDMA | Frequency Division Multiple Access | | |
| FR | Full Rate | | |
| GMSK | Gaussian Minimum Shift Keying | | |
| GPIO | General Purpose Input/Output | | |
| GPRS | General Packet Radio Service | | |
| GSM | Global Standard for Mobile Communications | | |
| HiZ | High Impedance | | |
| HR | Half Rate | | |
| I/O | Input/Output | | |
| IC | Integrated Circuit | | |
| IMEI | International Mobile Equipment Identity | | |
| ISO | International Standards Organization | | |
| ITU | International Telecommunications Union | | |
| kbps | kbits per second | | |
| LED | Light Emitting Diode | | |
| Li-Ion/Li+ | Lithium-Ion | | |
| Li battery | Rechargeable Lithium Ion or Lithium Polymer battery | | |
| LTE | Long Term Evolution | | |

| Abbreviation | Description |
|--------------|------------------------------------------------------------------------------------------------|
| Mbps | Mbits per second |
| MMI | Man Machine Interface |
| MO | Mobile Originated |
| MS | Mobile Station (GSM module), also referred to as TE |
| MSISDN | Mobile Station International ISDN number |
| MT | Mobile Terminated |
| NTC | Negative Temperature Coefficient |
| OEM | Original Equipment Manufacturer |
| PA | Power Amplifier |
| PAP | Password Authentication Protocol |
| PBCCH | Packet Switched Broadcast Control Channel |
| PCB | Printed Circuit Board |
| PCL | Power Control Level |
| PCM | Pulse Code Modulation |
| PCN | Personal Communications Network, also referred to as DCS 1800 |
| PCS | Personal Communication System, also referred to as GSM 1900 |
| PDU | Protocol Data Unit |
| PLL | Phase Locked Loop |
| PPP | Point-to-point protocol |
| PSK | Phase Shift Keying |
| PSU | Power Supply Unit |
| PWM | Pulse Width Modulation |
| R&TTE | Radio and Telecommunication Terminal Equipment |
| RAM | Random Access Memory |
| RF | Radio Frequency |
| RLS | Radio Link Stability |
| RMS | Root Mean Square (value) |
| RoHS | Restriction of the use of certain hazardous substances in electrical and electronic equipment. |
| ROM | Read-only Memory |
| RTC | Real Time Clock |
| RTS | Request to Send |
| Rx | Receive Direction |
| SAR | Specific Absorption Rate |
| SAW | Surface Accoustic Wave |
| SELV | Safety Extra Low Voltage |
| SIM | Subscriber Identification Module |
| SMD | Surface Mount Device |

| Abbreviation | Description |
|--------------|---------------------------------------------|
| SMS | Short Message Service |
| SMT | Surface Mount Technology |
| SRAM | Static Random Access Memory |
| TA | Terminal adapter (e.g. GSM module) |
| TDMA | Time Division Multiple Access |
| TE | Terminal Equipment, also referred to as DTE |
| TLS | Transport Layer Security |
| Tx | Transmit Direction |
| UART | Universal asynchronous receiver-transmitter |
| URC | Unsolicited Result Code |
| USSD | Unstructured Supplementary Service Data |
| VSWR | Voltage Standing Wave Ratio |

6.4 Safety Precaution Notes

The following safety precautions must be observed during all phases of the operation, usage, service or repair of any cellular terminal or mobile incorporating ELS31-V. Manufacturers of the cellular terminal are advised to convey the following safety information to users and operating personnel and to incorporate these guidelines into all manuals supplied with the product. Failure to comply with these precautions violates safety standards of design, manufacture and intended use of the product. Gemalto M2M assumes no liability for customer's failure to comply with these precautions.



7 Appendix

7.1 List of Parts and Accessories

Table 13: List of parts and accessories

| Description | Supplier | Ordering information |
|-----------------------------------------------------------------------------|-------------|--------------------------------------------------------------------------------------------------------------------------------|
| ELS31-V | Gemalto M2M | Standard module Gemalto M2M IMEI: Packaging unit (ordering) number: L30960-N4500-A200 Module label number: S30960-S4500-A200-1 |
| ELS51-V | Gemalto M2M | Standard module Gemalto M2M IMEI: Packaging unit (ordering) number: L30960-N4530-A100 Module label number: S30960-S4530-A100-1 |
| ELS31-V Evaluation Module | Gemalto M2M | Ordering number: L30960-N4501-A200 |
| ELS51-V Evaluation Module | Gemalto M2M | Ordering number: L30960-N4531-A100 |
| DSB75 Evaluation Kit | Gemalto M2M | Ordering number: L36880-N8811-A100 |
| DSB Mini Compact Evaluation Board | Gemalto M2M | Ordering number: L30960-N0030-A100 |
| Starter Kit B80 | Gemalto M2M | Ordering Number L30960-N0040-A100 |
| Multi-Adapter R1 for mounting ELS31-V/ELS51-V evaluation modules onto DSB75 | Gemalto M2M | Ordering number: L30960-N0010-A100 |
| Approval adapter for mounting ELS31-V/ELS51-V evaluation modules onto DSB75 | Gemalto M2M | Ordering number: L30960-N2301-A100 |
| SIM card holder incl. push button ejector and slide-in tray | Molex | Ordering numbers: 91228 91236 Sales contacts are listed in Table 14. |

Table 14: Molex sales contacts (subject to change)

| Molex For further information please click: http://www.molex.com | Molex Deutschland GmbH Otto-Hahn-Str. 1b 69190 Walldorf Germany Phone: +49-6227-3091-0 Fax: +49-6227-3091-8100 Email: mxgermany@molex.com | American Headquarters Lisle, Illinois 60532 U.S.A. Phone: +1-800-78MOLEX Fax: +1-630-969-1352 |
|---------------------------------------------------------------------------------------------------------------------------------------------------------------------------|-------------------------------------------------------------------------------------------------------------------------------------------|------------------------------------------------------------------------------------------------------------------------------------------------|
| Molex China Distributors Beijing, Room 1311, Tower B, COFCO Plaza No. 8, Jian Guo Men Nei Street, 100005 Beijing P.R. China Phone: +86-10-6526-9628 Fax: +86-10-6526-9730 | Molex Singapore Pte. Ltd. 110, International Road Jurong Town, Singapore 629174 Phone: +65-6-268-6868 Fax: +65-6-265-6044 | Molex Japan Co. Ltd. 1-5-4 Fukami-Higashi, Yamato-City, Kanagawa, 242-8585 Japan Phone: +81-46-265-2325 Fax: +81-46-265-2365 |

About Gemalto

Gemalto (Euronext NL0000400653 GTO) is the world leader in digital security with 2014 annual revenues of €2.5 billion and blue-chip customers in over 180 countries. Our 14,000 employees operate out of 99 offices, 34 personalization and data centers, and 24 research and software development centers located in 46 countries.

We are at the heart of the rapidly evolving digital society. Billions of people worldwide increasingly want the freedom to communicate, travel, shop, bank, entertain and work - anytime, everywhere - in ways that are enjoyable and safe. Gemalto delivers on their expanding needs for personal mobile services, payment security, authenticated cloud access, identity and privacy protection, eHealthcare and eGovernment efficiency, convenient ticketing and dependable machine-to-machine (M2M) applications.

Gemalto develops secure embedded software and secure products which we design and personalize. Our platforms and services manage these secure products, the confidential data they contain and the trusted end-user services they enable. Our innovations enable our clients to offer trusted and convenient digital services to billions of individuals.

Gemalto thrives with the growing number of people using its solutions to interact with the digital and wireless world.

For more information please visit

m2m.gemalto.com, www.facebook.com/gemalto, or Follow@gemaltom2m on twitter.

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